**Product End-of-Life Disassembly Instructions**

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

HP Pavilion Notebook
HP Pavilion Notebook 17

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

**1.0 Items Requiring Selective Treatment**

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB, USB board, Power board, TouchPad</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Cell battery, RTC</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery module
2. Dis-fasten All Base screw*20
3. Disassemble Base cap
4. Dis-fasten Base cap screw*4
5. Remove ODD
6. Disassemble Base
7. Pull out FFC*3(Touchpad, Power, USB)
8. Pull out FFC*2(HDD, ODD)
9. Pull out KB membrane, backlit(backlit sku only)
10. Pull out HDD module
11. Dis-fasten daughter boards screw*2 (USB)
12. Remove daughter board (USB)
13. Pull out wire cable connectors*3 (LCD, DC cable, Battery cable)
14. Pull out wire cable*2 (speaker, Fan)
15. Pull out Antenna
16. Dis-fasten Hinge screw*4
17. Remove hinge up
18. Dis-fasten Power board screw*2
19. Remove daughter board(Power)
20. Remove Batter cable
21. Remove ODD cable
22. Dis-fasten motherboard screw*5
23. Dis-fasten Fan screw*2
24. Remove Fan
25. Remove motherboard
26. Dis-fasten Speaker R&L screw*1
27. Remove speaker L & R
28. Dis-fasten thermal module screw*6
29. Remove thermal module
30. Remove LCD Bezel screw pad
31. Dis-fasten LCD Bezel screws*2
32. Remove LCD bezel
33. Dis-fasten Hinge BKT screw*6
34. Dis-fasten LCD BKT L & R screws*4
35. Remove LCD module
36. Remove Camera module
37. Remove Antenna cables L & R

EL-MF877-00
Template Revision B

PSG instructions for this template are available at EL-MF877-01
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly

![Total part disassembly](image1)

3.22 Remove battery module

![Remove battery module](image2)

3.23 Remove bottom cover

![Remove bottom cover](image3)
3.24 LCD module set disassembly

3.25 Base case disassembly

3.26 Thermal module and mother board disassembly
3.27 Top case disassembly